

# TMBF Plastic-Encapsulate Bridge Rectifier

## FAST RECOVERY SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

### Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Surge Current Capability
- Designed for Surface Mount Application
- Plastic Material – UL Flammability 94V-O

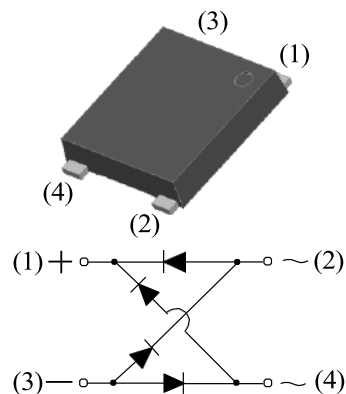
### Applications

- General purpose 1 phase Bridge rectifier applications

### Marking

- RTMBF310

TMBF



### Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions	RTMBF310
Repetitive Peak Reverse Voltage	$V_{RRM}$	V		1000
Maximum RMS Voltage	$V_{RMS}$	V		700
Maximum DC Blocking Voltage	$V_{DC}$	V		1000
Average Rectified Output Current	$I_o$	A	60Hz sine wave, R-load, $T_a=110^{\circ}C$ On alumina substrate	3.0
Surge(Non-repetitive)Forward Current	$I_{FSM}$	A	8.3ms sine wave, 1 cycle, $T_j=25^{\circ}C$	110
Current Squared Time	$I^2t$	A <sup>2</sup> S	$1ms \leq t < 8.3ms$ $T_j=25^{\circ}C$ , Rating of per diode	51
Operation Junction and Storage Temperature Range	$T_j, T_{stg}$	$^{\circ}C$		-55 ~ +150

### Electrical Characteristics (T=25 $^{\circ}C$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition	Max	
Maximum Peak Forward Voltage	$V_{FM}$	V	$I_{FM}=3.0A$ , Pulse measurement, Rating of per diode	1.25	
Maximum Reverse Recovery Time	$T_{RR}$	ns	Measured with $I_F=0.5A, I_R=1A, I_{RR}=0.25A$	500	
Maximum Peak Reverse Current	$I_{RRM1}$	$\mu A$	$V_{RM}=V_{RRM}$ , Pulse measurement, Rating of per diode	$T_A=25^{\circ}C$	5.0
	$I_{RRM2}$	$\mu A$		$T_A=125^{\circ}C$	500
Thermal Resistance	$R_{\theta J-A}$	$^{\circ}C/W$	Between junction and ambient, On alumina substrate	55	
	$R_{\theta J-L}$		Between junction and lead	15	
	$R_{\theta J-C}$		Between junction and case	10	

**Typical Characteristics**

FIG.1: FORWARD CURRENT DERATING CURVE

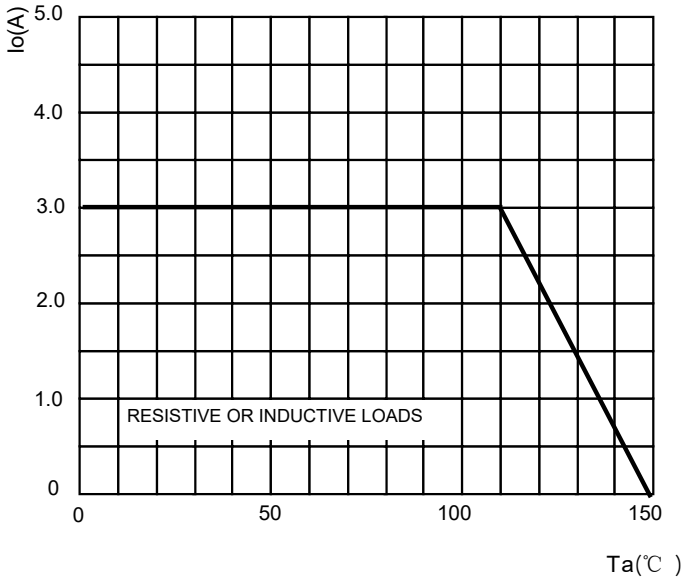


FIG.2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

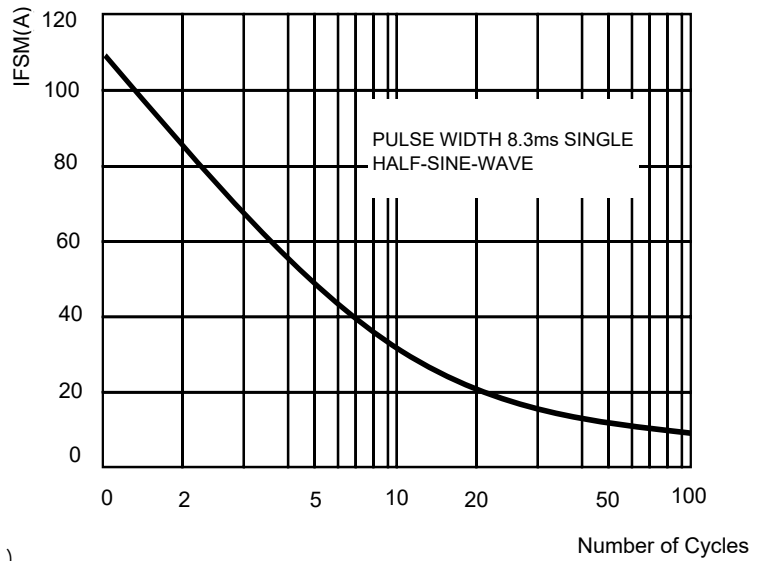


FIG.3: TYPICAL FORWARD CHARACTERISTICS

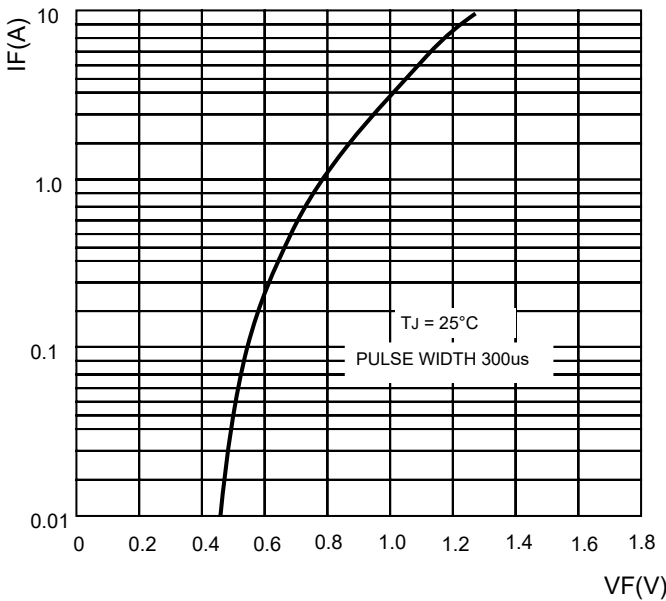


FIG.4: TYPICAL REVERSE CHARACTERISTICS

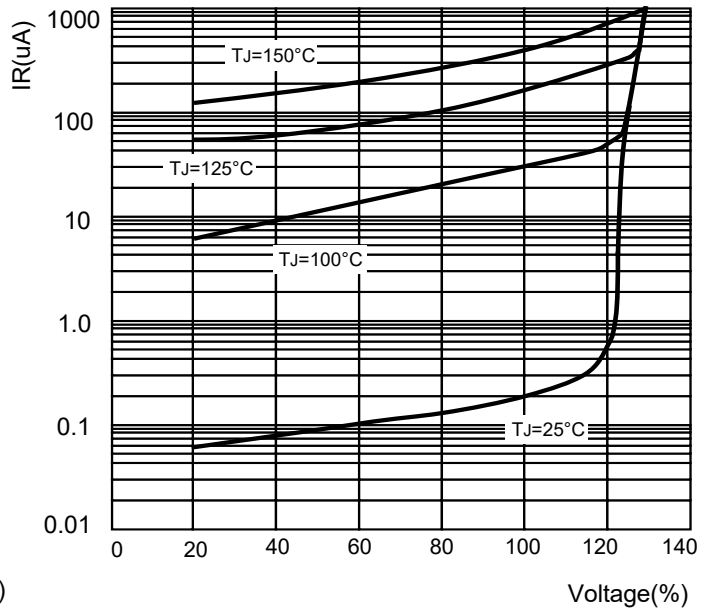
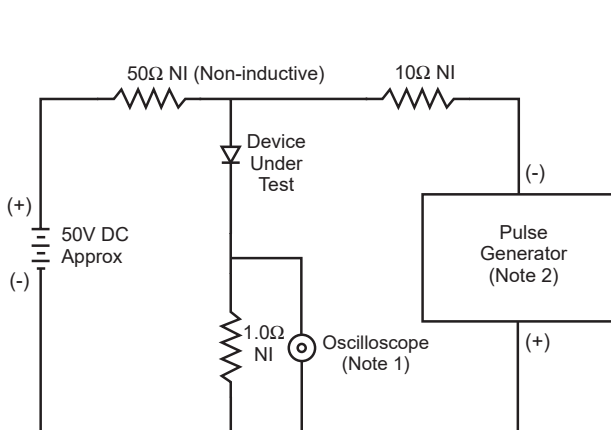
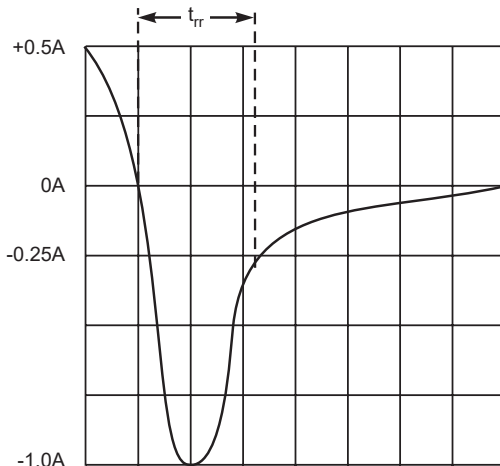


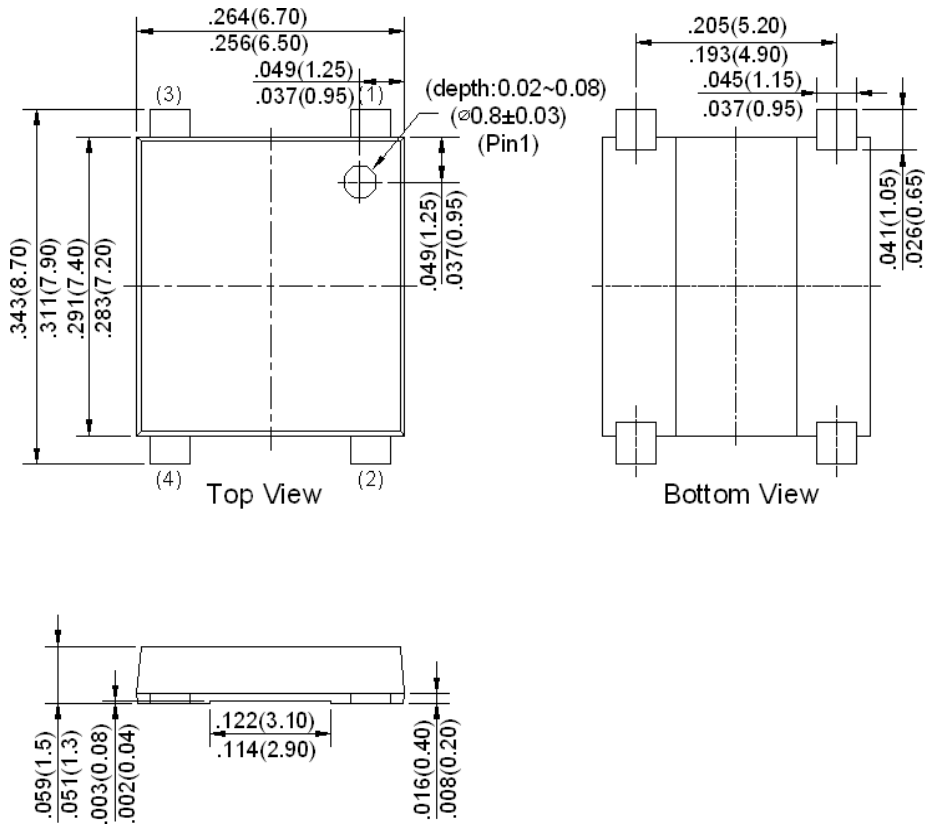
FIG5 Reverse Recovery Time Characteristic and Test Circuit



Notes:  
 1. Rise Time = 7.0ns max. Input Impedance = 1.0MΩ, 22pF.  
 2. Rise Time = 10ns max. Input Impedance = 50Ω.

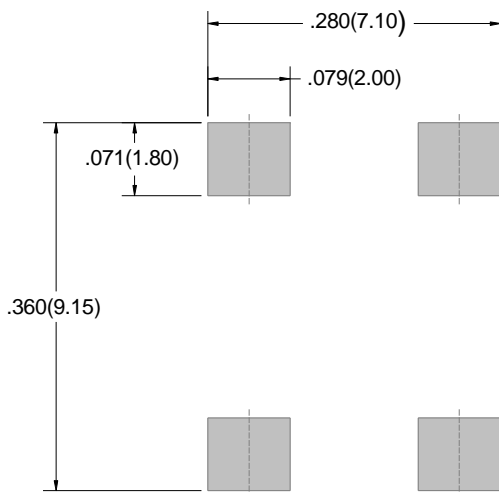


### TMBF Package Outline Dimensions



Dimensions in inches and (millimeters)

### TMBF Suggested Pad Layout



**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05$ mm.
3. The pad layout is for reference purposes only.